

123-98



Form PTO-1595

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1-31-92

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<p>1. Name of conveying party(ies) Mark V. Pierson</p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>2. Name and address of receiving party(ies): Name: <u>International Business Machines Corporation</u></p> <p>Internal Address: Street Address: <u>New Orchard Road</u> City: <u>Armonk</u> State: <u>New York</u> Zip: <u>10504</u></p>			
<p>3. Nature of conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of name <input type="checkbox"/> Other</p> <p>Execution Date: <u>11/12/1998</u></p>	<p>Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>			
<p>4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: <u>11/12/1998</u></p> <table style="width: 100%; border: none;"> <tr> <td style="width: 50%; border: none;"> <p>A. Patent Application No.(s) <u>EN998077</u></p> </td> <td style="width: 50%; border: none;"> <p>B. Patent No.(s)</p> </td> </tr> </table> <p style="text-align: center;">Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>		<p>A. Patent Application No.(s) <u>EN998077</u></p>	<p>B. Patent No.(s)</p>	
<p>A. Patent Application No.(s) <u>EN998077</u></p>	<p>B. Patent No.(s)</p>			
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: <u>Pollock, Vande Sande & Amernick</u></p> <p>Internal Address: <u>P.O. Box 19088</u> Street Address: <u>1990 M Street, N.W.</u> <u>Suite 800</u> City: <u>Washington</u> State: <u>D.C.</u> Zip: <u>20036</u></p>	<p>6. Total number of applications and patents involved <u>1</u></p> <p>7. Total fee (37 CFR 3.41) <u>\$40</u> <input type="checkbox"/> Enclosed <input checked="" type="checkbox"/> Authorized to be charged to deposit account</p> <p>8. Deposit Account No: <u>09-0457</u> <u>(International Business Machines Corporation)</u> (Attach duplicate copy of this page if paying by deposit account)</p>			
<p>DO NOT USE THIS SPACE</p>				
<p>9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</p> <table style="width: 100%; border: none;"> <tr> <td style="width: 30%;"> <p>Lawrence R. Fraley Reg. No. 26,885 Name of Person Signing</p> </td> <td style="width: 40%; text-align: center;"> <p>Signature</p> </td> <td style="width: 30%; text-align: center;"> <p><u>Dec. 02, 1998</u> Date</p> </td> </tr> </table> <p style="text-align: right;">Total number of pages comprising cover sheet: <u>1</u></p>		<p>Lawrence R. Fraley Reg. No. 26,885 Name of Person Signing</p>	 <p>Signature</p>	<p><u>Dec. 02, 1998</u> Date</p>
<p>Lawrence R. Fraley Reg. No. 26,885 Name of Person Signing</p>	 <p>Signature</p>	<p><u>Dec. 02, 1998</u> Date</p>		
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PATENT
REEL: 9644 FRAME: 0505

IBM Docket No.:
EN998077

ASSIGNMENT

Whereas, we

Inventor and City	(1) Mark V. Pierson County of Broome	City of Binghamton and State of New York
and	(2) County of	City of and State of
and	(3) County of	City of and State of
and	(4) County of	City of and State of
and	(5) County of	City of and State of
and	(6) County of	City of and State of
and	(7) County of	City of and State of
and	(8) County of	City of and State of

have invented certain improvements in

Title **PANEL STRUCTURE WITH PLURALITY OF CHIP COMPARTMENTS FOR PROVIDING HIGH VOLUME OF CHIP MODULES**

Dates That Inventors Signed the Declaration **and have executed, respectively, a United States patent application therefor on**

(1) 11/12/98	and, (2)	and,
(3)	and, (4)	and,
(5)	and, (6)	and,
(7)	and, (8)	

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

(Signatures of Inventors on Page 2)

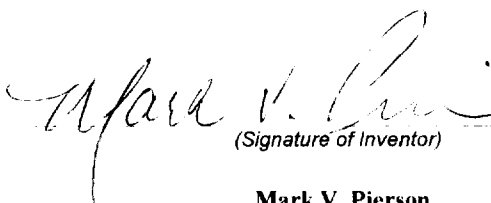
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ASSIGNMENT (Continued)

Title **PANEL STRUCTURE WITH PLURALITY OF CHIP COMPARTMENTS FOR PROVIDING HIGH VOLUME OF CHIP MODULES**

City (1) Signed at ENDICOTT NY
Date on 11/18/92



(Signature of Inventor)

Mark V. Pierson
(Typed Name of Inventor)

City (2) Signed at
Date on

(Signature of Inventor)

(Typed Name of Inventor)

City (3) Signed at
Date on

(Signature of Inventor)

(Typed Name of Inventor)

City (4) Signed at
Date on

(Signature of Inventor)

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Date on

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Date on

(Signature of Inventor)

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